



1.6x0.8x0.5mm BI-COLOR SURFACE MOUNT LED

Features

• 1.6mm X 0.8mm SMD LED

• Package height: 0.5mm

ullet IR-reflow compatible

• Standard Package: 2,000pcs/ Reel

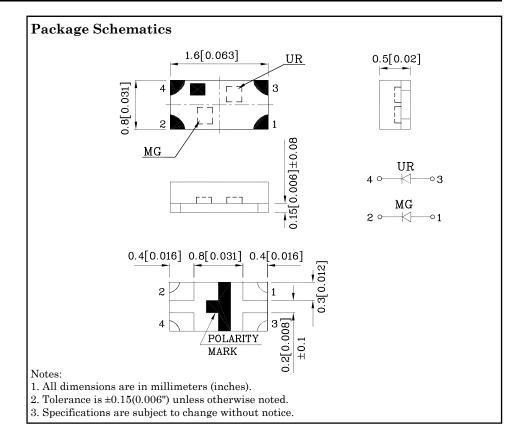
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• MSL (Moisture Sensitivity Level): 3

• RoHS compliant







Absolute Maximum Ratings (T _A =25°C)		MG (GaP)	UR (GaAsP/ GaP)	Unit
Reverse Voltage	V_{R}	5	5	V
Forward Current	I_{F}	25	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	140	160	mA
Power Dissipation	P_D	62.5	75	mW
Operating Temperature	$T_{\rm A}$	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		C

Operating Characteristics (T _A =25°C)	MG (GaP)	UR (GaAsP/ GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2.2	2	V
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	2.5	2.5	V
Reverse Current (Max.) (V_R =5 V)	I_{R}	10	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	565*	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	568*	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	30	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	15	pF

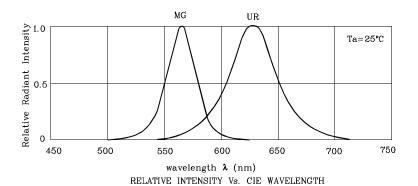
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}20\text{mA}) \ mcd \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMGUR53W-9	Green	GaP	Water Clear	5 5*	14 14*	565*	130°
	Red	GaAsP/GaP		7 5*	14 11*	627*	

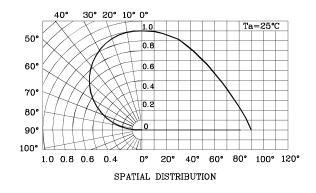
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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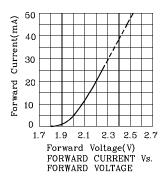


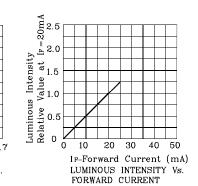


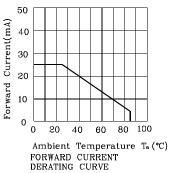


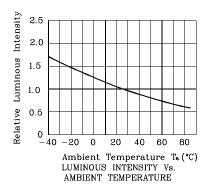


❖ MG

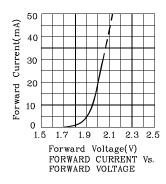


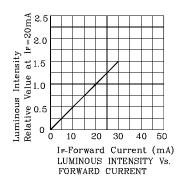


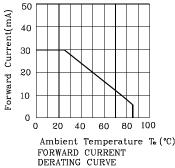


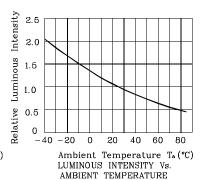


❖ UR





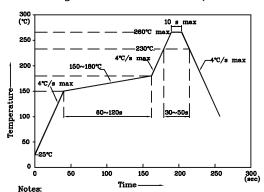






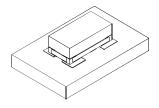
LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

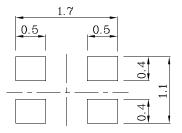


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

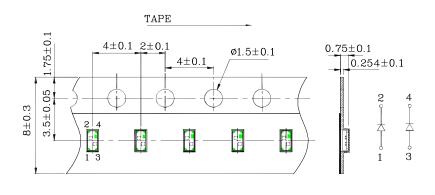
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



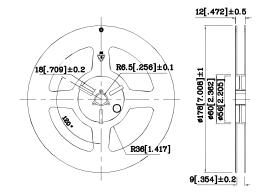
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Tape Specification (Units:mm)



❖ Reel Dimension



Remarks:

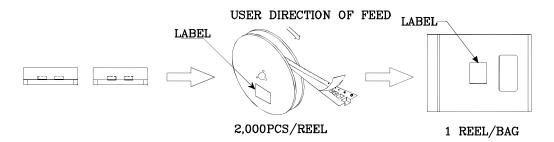
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

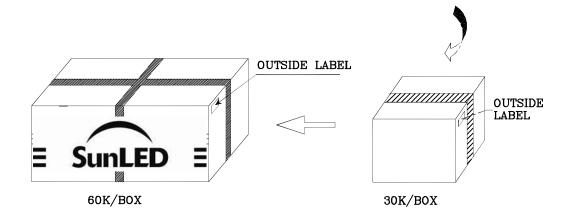
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

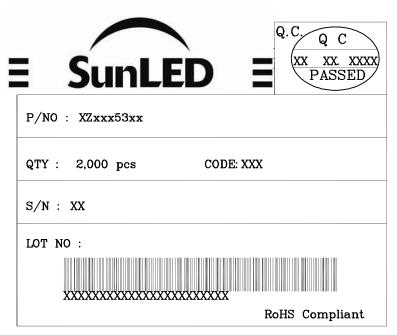
Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS







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